MA3X717D (MA717WA), MA3X717E (MA717WK)

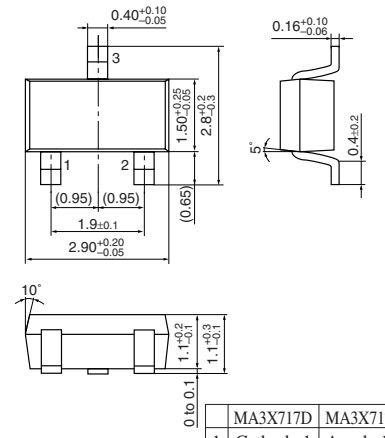
Silicon epitaxial planar type

For switching

■ Features

- Two MA3X717 (MA717) is contained in one package
- Forward voltage V_F, optimum for low voltage rectification
- Low V_F type of MA3X704D (MA704WA), MA3X704E (MA704WK)
- Optimum for high frequency rectification because of its short reverse recovery time (t_{rr})

Unit: mm



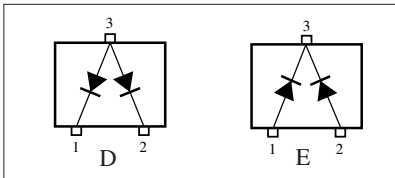
	MA3X717D	MA3X717E
1	Cathode 1	Anode 1
2	Cathode 2	Anode 2
3	Anode	Cathode

EIAJ: SC-59
Mini3-G1 Package

Marking Symbol

- MA3X717D: M3E
- MA3X717E: M3D

Internal Connection



■ Absolute Maximum Ratings $T_a = 25°C$

Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	30	V
Maximum peak reverse voltage		V_{RM}	30	V
Forward current	Single	I_F	30	mA
	Double		20	
Peak forward current	Single	I_{FM}	150	mA
	Double		110	
Junction temperature		T_j	125	°C
Storage temperature		T_{stg}	−55 to +125	°C

■ Electrical Characteristics T_a=25°C ± 3°C

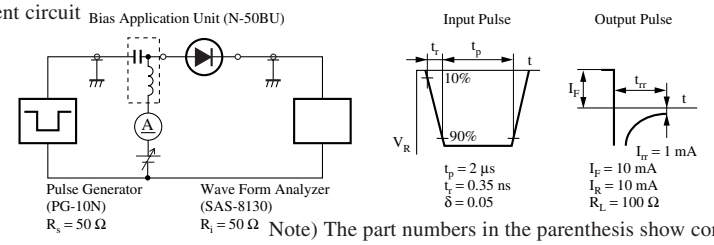
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	I_F = 1 mA			0.3	V
	V_{F2}	I_F = 30 mA			1.0	
Reverse current	I_R	V_R = 30 V			30	µA
Terminal capacitance	C_t	V_R = 1 V, f = 1 MHz		1.5		pF
Reverse recovery time *	t_{rr}	$I_F = I_R$ = 10 mA I_{rr} = 1 mA , R_L = 100 Ω		1.0		ns
Detection efficiency	η	V_{IN} = 3 $V_{(peak)}$, f = 30 MHz R_L = 3.9 kΩ, C_L = 10 pF		65		%

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

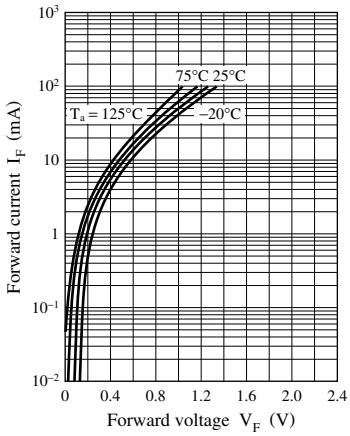
3. Absolute frequency of input and output is 2 GHz.

4. ∗: t_{rr} measurement circuit

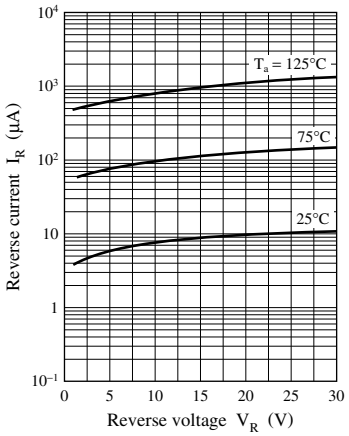


Note) The part numbers in the parenthesis show conventional part number.

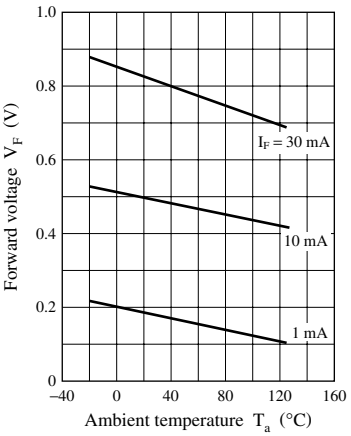
I_F — V_F



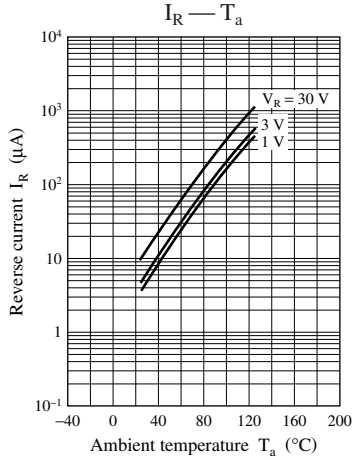
I_R — V_R



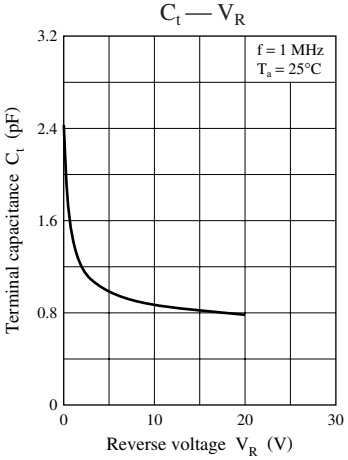
V_F — T_a



I_R — T_a



C_t — V_R



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